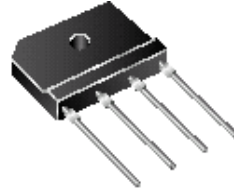


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Features

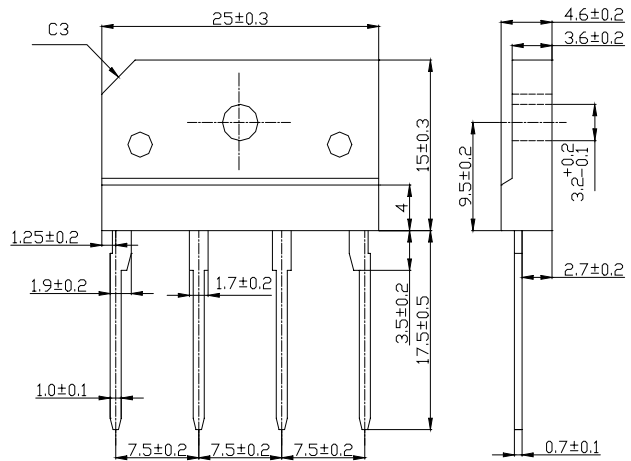
- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- High case dielectric strength of 2000 V_{RMS}
- Ideal for printed circuit boards
- Glass passivated chip junction
- Ultra surge current capability
- UL Recognized File # E223064



Case Style: KBJ (3S)

Mechanical Data

- Case: KBJ(3S) Molded plastic body
 - Mounting Position: Any⁽³⁾
 - Mounting Torque: 5 in. – lb. Max.
 - Weight: 0.15oz., 4.3g
 - Terminals: Plated Leads Solderable per MIL-STD-750, Method 2026
- High temperature soldering guaranteed:
260°C/10 seconds, 0.375(9.5mm) lead length,
5lbs.(2.3kg) tension



Maximum Ratings and Electrical Characteristics @T_A=25°C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	KBJ4AV	KBJ4BV	KBJ4DV	KBJ4GV	KBJ4JV	KBJ4KV	KBJ4MV	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	V _{R(RMS)}	35	70	140	280	420	560	700	V
Average Rectified Output Current @T _C = 100°C @T _A = 25°C	I _O	4.0 ⁽¹⁾ 2.3 ⁽²⁾							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	150							A
I ² t Rating for Fusing (t < 8.3ms)	I ² t	93							A ² s
Forward Voltage (per diode) @I _F = 2.0A	V _{FM}	1.00							V
Peak Reverse Current At Rated DC Blocking Voltage @T _A = 25°C @T _C = 125°C	I _R	5.0 250							µA
Typical Thermal Resistance (per leg) (Note 1)	R _{θJA}	26 ⁽²⁾							K/W
Typical Thermal Resistance (per leg) (Note 2)	R _{θJC}	5 ⁽¹⁾							K/W
Dielectric strength(Terminals to case, AC 1 minute)	V _{dis}	2000							V
Operating and Storage Temperature Range	T _j , T _{STG}	-55 to +150							°C

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- Note: (1) Unit case mounted on AL plate heatsink
 (2) Unit mounted on P.C.B. with 0.5x0.5"(12x12mm) copper pads and 0.375"(9.5mm) lead length without heatsink.
 (3) Recommended mounting position is to bolt down on heatsink with silicone thermal compound for maximum heat transfer with #6 screw

Fig. 1 – Derating Curve Output Rectified Current

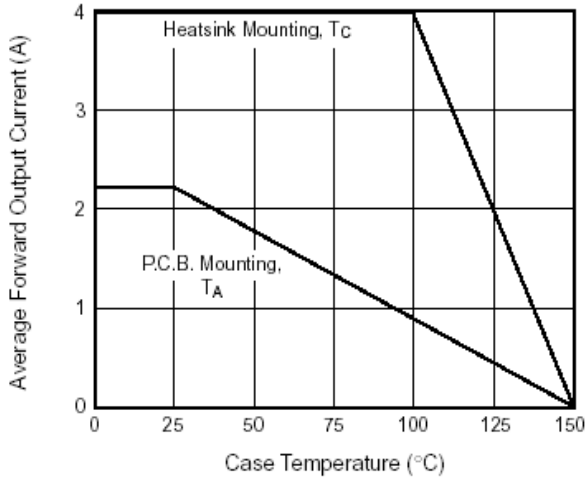


Fig. 2 – Maximum Non-Repetitive Peak Forward Surge Current Per Leg

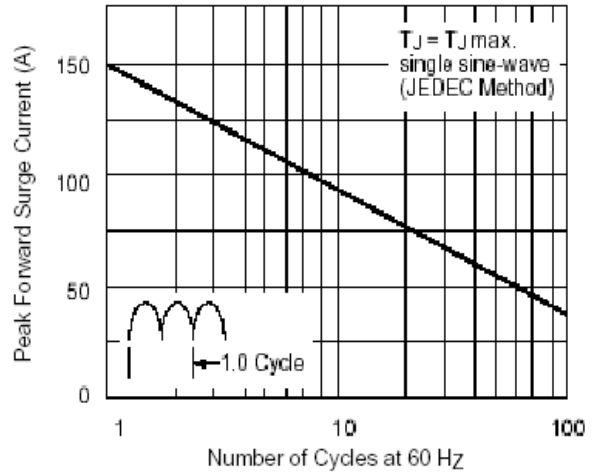


Fig. 3 – Typical Instantaneous Forward Characteristics Per Leg

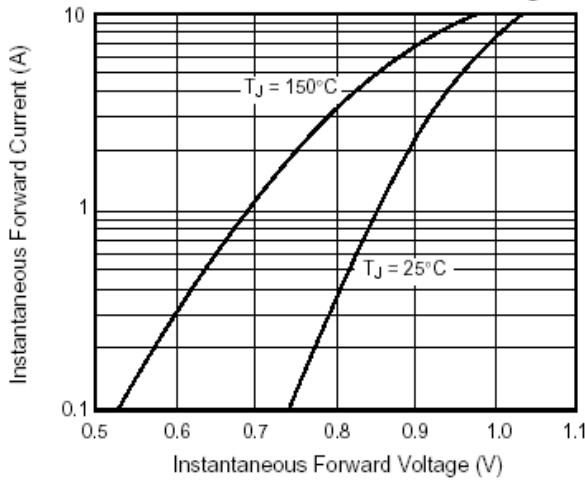


Fig. 4 – Typical Reverse Characteristics Per Leg

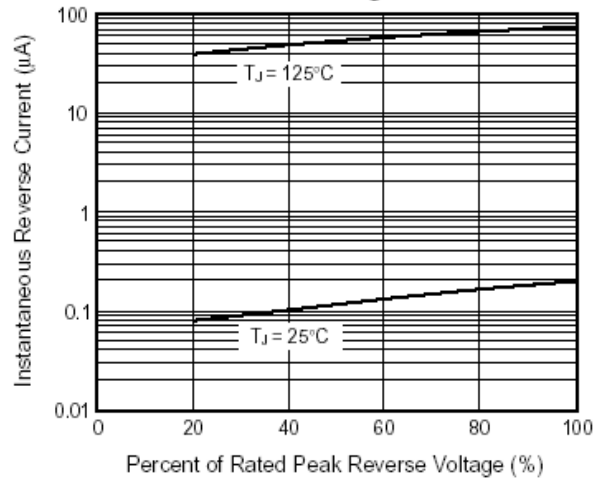


Fig. 5 – Typical Junction Capacitance Per Leg

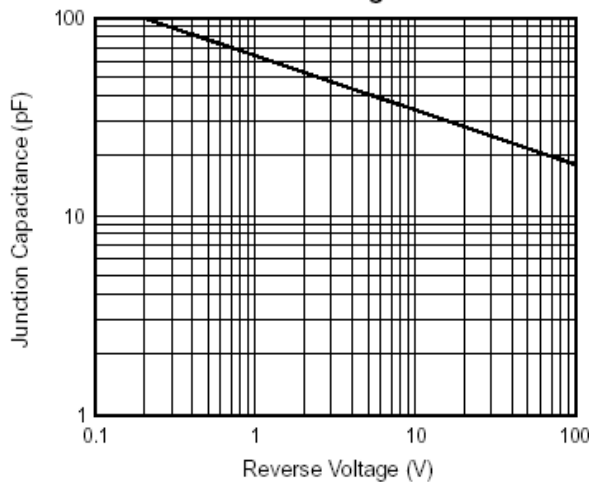
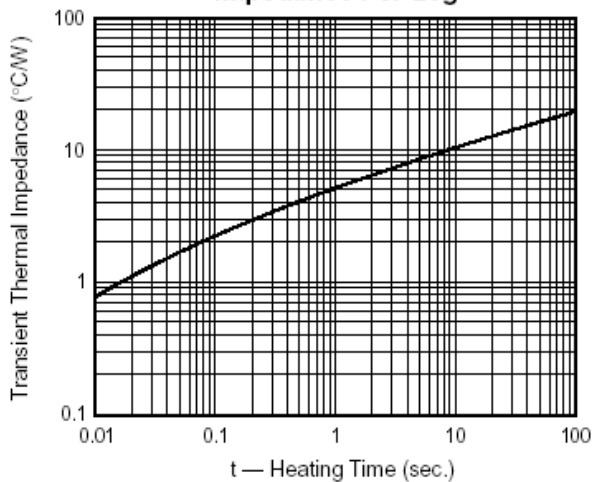


Fig. 6 – Typical Transient Thermal Impedance Per Leg



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